MOSFETs Silicon N-Channel MOS (DTMOSVI)

# TK125Z60Z1

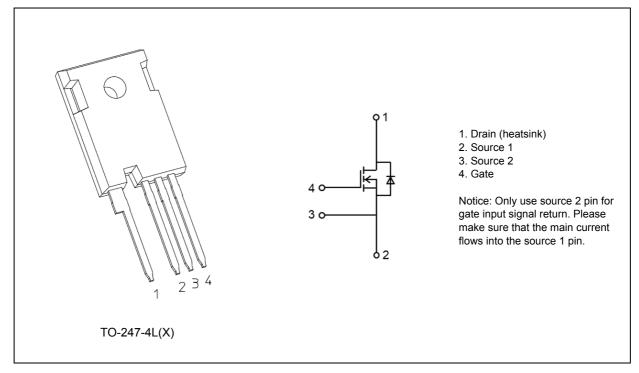
#### 1. Applications

• Switching Power Supplies

#### 2. Features

- (1) Low drain-source on-resistance:  $R_{DS(ON)} = 0.105 \Omega$  (typ.)
- (2) High-speed switching properties with the lower capacitance.
- (3) Enhancement mode:  $V_{th}$  = 3 to 4 V ( $V_{DS}$  = 10 V,  $I_D$  = 0.73 mA)

#### 3. Packaging and Internal Circuit



#### 4. Absolute Maximum Ratings (Note) ( $T_a = 25 \ ^{\circ}C$ unless otherwise specified)

| Characteristics                | Symbol                   | Rating           | Unit       |       |
|--------------------------------|--------------------------|------------------|------------|-------|
| Drain-source voltage           |                          | V <sub>DSS</sub> | 600        | V     |
| Gate-source voltage            |                          | V <sub>GSS</sub> | ±30        |       |
| Drain current (DC)             | (Note 1)                 | Ι <sub>D</sub>   | 20         | A     |
| Drain current (pulsed)         | (Note 1)                 | I <sub>DP</sub>  | 80         |       |
| Power dissipation (            | (T <sub>c</sub> = 25 °C) | PD               | 150        | W     |
| Single-pulse avalanche energy  | (Note 2)                 | E <sub>AS</sub>  | 242        | mJ    |
| Single-pulse avalanche current |                          | I <sub>AS</sub>  | 4.2        | A     |
| Reverse drain current (DC)     | (Note 1)                 | I <sub>DR</sub>  | 20         |       |
| Reverse drain current (pulsed) | (Note 1)                 | I <sub>DRP</sub> | 80         |       |
| Channel temperature            |                          | T <sub>ch</sub>  | 150        | ů     |
| Storage temperature            |                          | T <sub>stg</sub> | -55 to 150 |       |
| Mounting torque                |                          | TOR              | 0.8        | N · m |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

| Characteristics                       | Symbol                | Max   | Unit |
|---------------------------------------|-----------------------|-------|------|
| Channel-to-case thermal resistance    | R <sub>th(ch-c)</sub> | 0.833 | °C/W |
| Channel-to-ambient thermal resistance | R <sub>th(ch-a)</sub> | 50    |      |

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: V\_{DD} = 90 V, T\_{ch} = 25 °C (initial), L = 24.3 mH, I\_{AS} = 4.2 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

#### 6. Electrical Characteristics

#### 6.1. Static Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

| Characteristics                | Symbol               | Test Condition                                   | Min | Тур.  | Max   | Unit |
|--------------------------------|----------------------|--|-----|-------|-------|------|
| Gate leakage current           | I <sub>GSS</sub>     | $V_{GS}$ = ±30 V, $V_{DS}$ = 0 V                 | _   | _     | ±1    | μA   |
| Drain cut-off current          | I <sub>DSS</sub>     | $V_{DS}$ = 600 V, $V_{GS}$ = 0 V                 | _   | _     | 2     |      |
| Drain-source breakdown voltage | V <sub>(BR)DSS</sub> | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V    | 600 | _     | _     | V    |
| Gate threshold voltage         | V <sub>th</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.73 mA | 3   | _     | 4     |      |
| Drain-source on-resistance     | R <sub>DS(ON)</sub>  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A     |     | 0.105 | 0.125 | Ω    |

#### 6.2. Dynamic Characteristics (Ta = 25 °C unless otherwise specified)

| Characteristics                               |          | Symbol             | Test Condition  | Min | Тур. | Max | Unit |
|---|----------|--------------------|---|-----|------|-----|------|
| Input capacitance                             |          | C <sub>iss</sub>   | V <sub>DS</sub> = 300 V, V <sub>GS</sub> = 0 V, f = 100 kHz | _   | 1620 | _   | pF   |
| Reverse transfer capacitance                  |          | C <sub>rss</sub>   |   | _   | 2.3  | _   |      |
| Output capacitance                            |          | C <sub>oss</sub>   |   | _   | 40   | _   |      |
| Effective output capacitance (energy related) | (Note 3) | C <sub>o(er)</sub> | $V_{DS}$ = 0 to 400 V, $V_{GS}$ = 0 V                       |     | 70   | _   |      |
| Effective output capacitance (time related)   | (Note 4) | C <sub>o(tr)</sub> | $V_{DS}$ = 0 to 400 V, $V_{GS}$ = 0 V                       |     | 480  | _   | pF   |
| Gate resistance                               |          | r <sub>g</sub>     | V <sub>DS</sub> = OPEN , f = 1 MHz                          | _   | 3.2  | _   | Ω    |
| Switching time (rise time)                    |          | t <sub>r</sub>     | See Fig. 6.2.1  | _   | 16   | _   | ns   |
| Switching time (turn-on time)                 |          | t <sub>on</sub>    |   | _   | 38   | _   | ns   |
| Switching time (fall time)                    |          | t <sub>f</sub>     |   | _   | 5    | _   |      |
| Switching time (turn-off time)                |          | t <sub>off</sub>   | ]   | _   | 75   | _   | ns   |
| MOSFET dv/dt ruggedness                       |          | dv/dt              | $V_{DS} \leq V_{DSS}, \ I_D \leq 10 \ A$                    | 70  |      | _   | V/ns |

Note 3:  $C_{O(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 V to 400 V. Note 4:  $C_{O(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 V to 400 V.

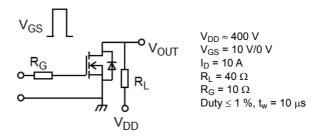


Fig. 6.2.1 Switching Time Test Circuit

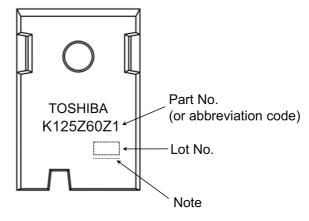
#### 6.3. Gate Charge Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

| Characteristics                                 | Symbol           | Test Condition  | Min | Тур. | Max | Unit |
|---|------------------|---|-----|------|-----|------|
| Total gate charge (gate-source plus gate-drain) | Qg               | $V_{DD} \approx 400$ V, $V_{GS}$ = 10 V, $I_D$ = 20 A | —   | 28   | —   | nC   |
| Gate-source charge 1                            | Q <sub>gs1</sub> |   |     | 9    | _   |      |
| Gate-drain charge                               | Q <sub>gd</sub>  |   |     | 8    | _   |      |

#### 6.4. Source-Drain Characteristics ( $T_a = 25$ °C unless otherwise specified)

| Characteristics               | Symbol           | Test Condition   | Min | Тур. | Max  | Unit |
|-------------------------------|------------------|--|-----|------|------|------|
| Diode forward voltage         | V <sub>DSF</sub> | I <sub>DR</sub> = 20 A, V <sub>GS</sub> = 0 V  | _   | _    | -1.7 | V    |
| Reverse recovery time         |                  | V <sub>DD</sub> = 400 V,   | _   | 285  | _    | ns   |
| Reverse recovery charge       | Q <sub>rr</sub>  | I <sub>DR</sub> = 10 A, V <sub>GS</sub> = 0 V<br>-dI <sub>DR</sub> /dt = 100 A/μs                    |     | 3.1  |      | μC   |
| Peak reverse recovery current | l <sub>rr</sub>  | $-di_{DR}/dt = 100 A/\mu s$  | _   | 22   | _    | А    |
| Diode dv/dt ruggedness        | dv/dt            | $V_{DD} \leq 400 \text{ V}, \text{ I}_{DR} \leq 10 \text{ A}, \text{ V}_{GS} \text{ = } 0 \text{ V}$ | 40  |      |      | V/ns |

#### 7. Marking (Note)





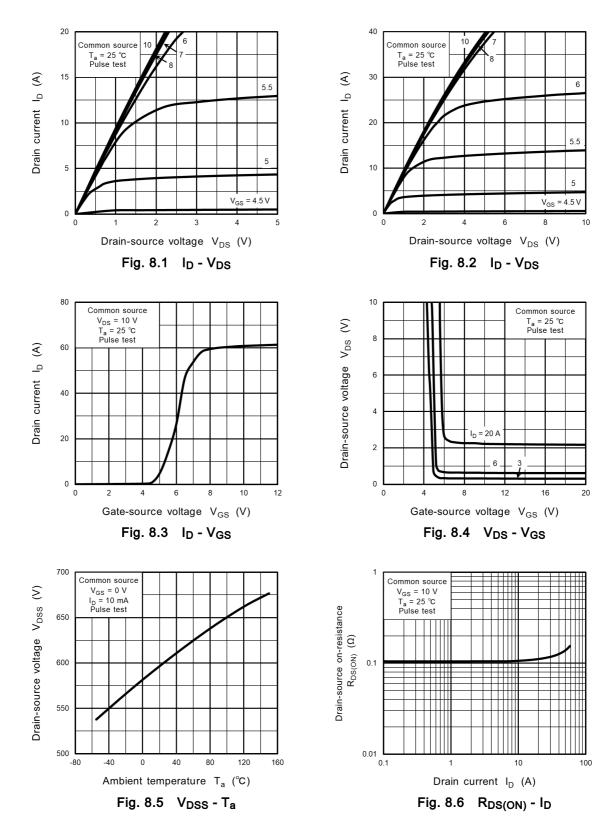
Note: A line under a Lot No. identifies the indication of product Labels. Not underlined: [[Pb]]/INCLUDES > MCV

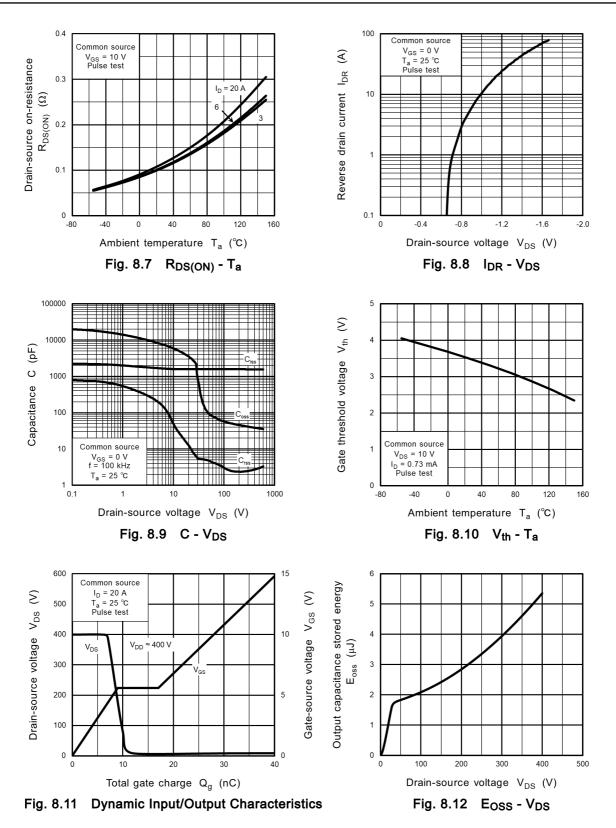
Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

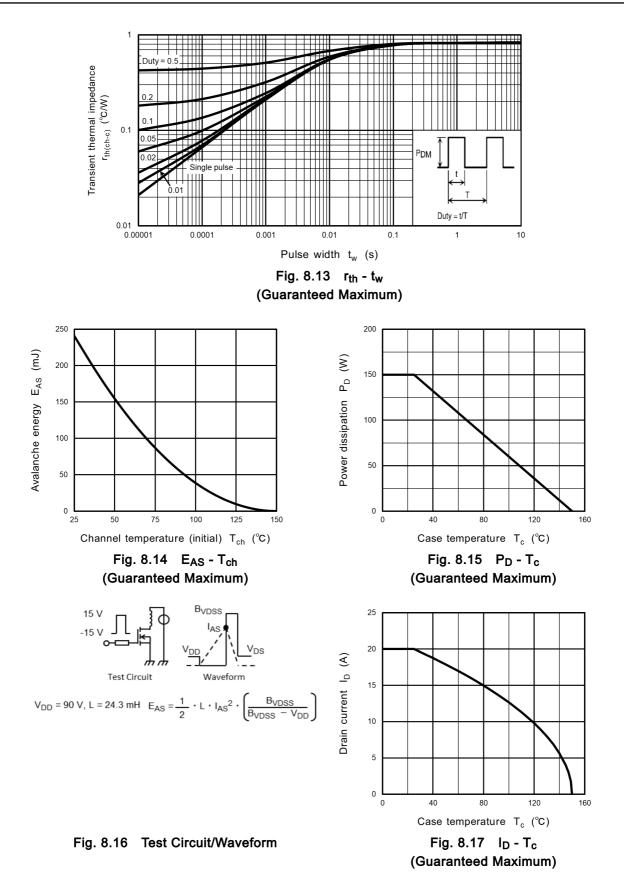
Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

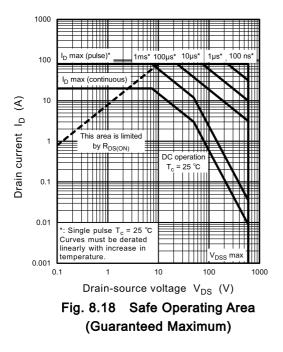
The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

#### 8. Characteristics Curves (Note)







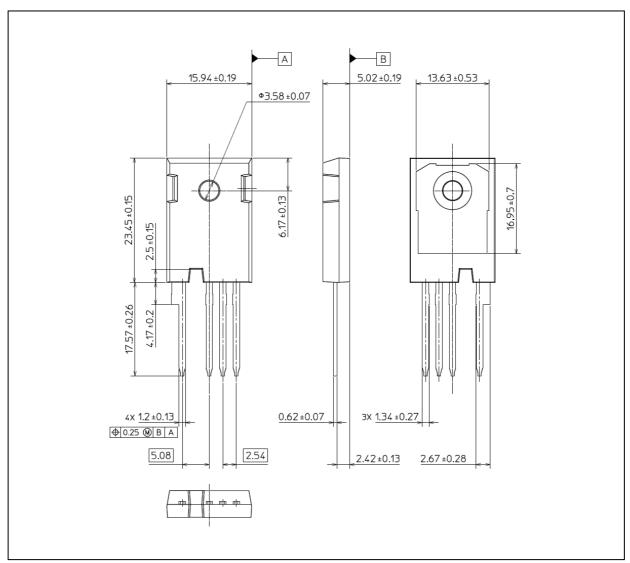


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

### TK125Z60Z1

#### **Package Dimensions**

Unit: mm



#### Weight: 6.55 g (typ.)

| Package Name(s)        |
|------------------------|
| TOSHIBA: 2-16M3A       |
| Nickname: TO-247-4L(X) |

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